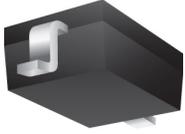


# MATERIAL DECLARATION SHEET



Package Type	CDSOD323-Txx					
Product Line	Semiconductor Products					
Compliance Date	January 9, 2026					
RoHS Compliant	Yes	Terminal	e3	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.003074	Amorphous Silica	60676-86-0	91.689	49.5352	54.0246
				Epoxy Resin A	Proprietary	4.167	2.2509	
				Epoxy Resin B	29690-82-2	1.414	0.7639	
				Phenol Resin	Proprietary	2.146	1.1595	
				Carbon Black	1333-86-4	0.583	0.3151	
2	Leadframe	Copper Alloy	0.002045	Copper	7440-50-8	97.399	35.0057	35.9403
				Iron	7439-89-6	2.389	0.8584	
				Phosphorus	7723-14-0	0.076	0.0274	
				Zinc	7440-66-6	0.127	0.0456	
		Lead	7439-92-1	0.009	0.0032			
		Silver Plating	0.000029	Silver	7440-22-4	100.000	0.5097	0.5097
3	Chip	Silicon	0.000283	Silicon	7440-21-3	91.072	4.5190	4.9736
				Nickel	7440-02-0	6.094	0.3030	
				Aluminum	7429-90-5	2.458	0.1328	
				Gold	7440-57-5	0.377	0.0188	
4	Die Attach	Silver Epoxy	0.000058	Silver	7440-22-4	95.190	0.9702	1.0193
				bisphenol-F-(epichlorohydrin); epoxy resin	9003-36-5	2.756	0.0281	
				1,4-bis(2,3 epoxypropoxy)butane	2425-79-8	1.061	0.0108	
				Aromatic polyamine	Proprietary	0.965	0.0098	
		adipic acid	124-04-9	0.028	0.0004			
5	Bond Wires	Copper	0.000027	Copper	7440-50-8	98.260	0.4663	0.4745
				Non - Cu element	Proprietary	1.740	0.0082	
6	Lead Finish	Matte Tin	0.000174	Tin	7440-31-5	100.000	3.0580	3.0580
		Total Weight	0.005690					

**Important remarks:**

1. It is responsibility of the user to verify they are accessing the latest version.